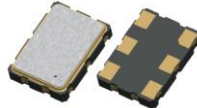


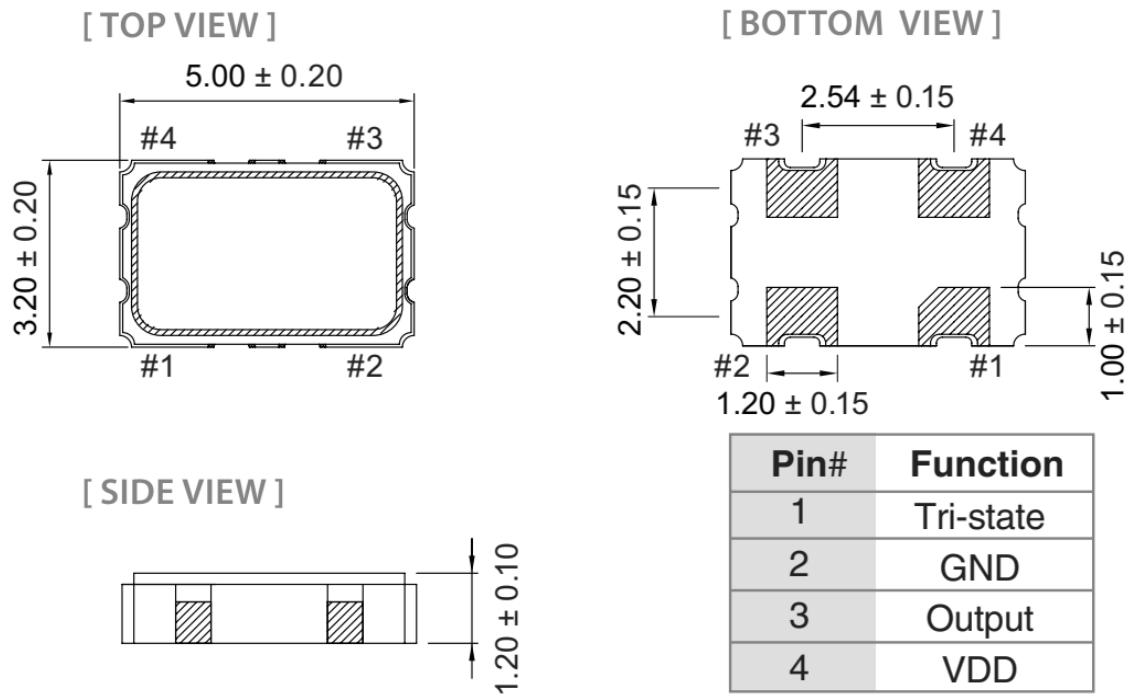
Features		Typical Application							
<ul style="list-style-type: none"> <li>● Typical 5.0 x 3.2 x 1.2 mm ceramic SMD package.</li> <li>● Conforms to AEC-Q200</li> <li>● Tight symmetry (45 to 55%) available.</li> <li>● Realize the standby function with Tri-State</li> </ul>		<ul style="list-style-type: none"> <li>● GPS, Mobile Phone</li> <li>● WLAN, Wireless, Fiber/10Gbit Ethernet</li> <li>● Notebook, PDA, DSC</li> </ul>							
BS5032A Series									
Parameter	3.3v		2.5V		1.8V		Unit	Conditions	
	Min.	Max.	Min.	Max.	Min.	Max.			
Supply Voltage Variation	VDD-10%	VDD+10%	VDD-10%	VDD+10%	VDD-10%	VDD+10%	V		
Frequency Range	0.0137	160	0.0137	160	0.0137	135	MHz		
Supply Frequency	2.048, 25, 26, 27, 50, 66.667, 100, 125						MHz		
Supply Current	-	1	-	1	-	1	mA	13.7kHz~93kHz	
	-	10	-	8	-	7		0.3125MHz~50MHz	
	-	20	-	18	-	15		40MHz~75MHz	
	-	35	-	30	-	25		75MHz~135MHz	
	-	45	-	40	-	-		≥135MHz	
Output Level (CMOS)	2.97	-	2.25	-	1.62	-	V	Output High	
	-	0.33	-	0.25	-	0.18		Output Low	
Transition Time: Rise/Fall Time	-	50	-	50	-	50	nSec	13.7kHz~93kHz	
	-	5	-	5	-	5		0.3125MHz~100MHz	
	-	3	-	3	-	3		≥100MHz	
Tri-State Mode (Input to Pin 1)	Enable	2.31	-	1.75	-	1.26	V		
	Disable	-	0.99	-	0.75	-		0.54	
Standby Current	-	10	-	10	-	10	uA		
Output Drive Capability (CL)	-	15	-	15	-	15	pF		
Period Jitter(Pk-Pk)	-	40	-	40	-	40	pSec		
RMS Phase Jitter	-	1	-	1	-	1	pSec	Integrated 12 kHz~20 MHz	
Startup Time	-	5	-	5	-	5	mSec		
Aging	-	±3	-	±3	-	±3	ppm	@ 25°C, First Year	
Storage Temp. Range	-55	125	-55	125	-55	125	°C		
FREQ. STABILITY vs. TEMP. RANGE		±20ppm		±25ppm		±50ppm			
	-10~+60	Available		Available		Available			
	-20~+70	Conditional		Available		Available			
	-40~+85	Conditional		Available		Available			
	-40~+125	Not Available		Not Available		Available			
<b>Note: not all combination of options are available. Other specifications may be available upon request.</b>									

## Reliability

Parameter	Condition
Temperature Stress Test	IEC60068, GJB360B
Mechanical Stress Test	IEC60068, GJB360B
EMC Test (ESD)	IEC61000, JESD22
Solderability	EIA/JESD22-B102-C
Contact Pads	Gold over Nickel
RoHS	RoHS Directive 2011/65/EU Annex II Recasting 2002/95/EC

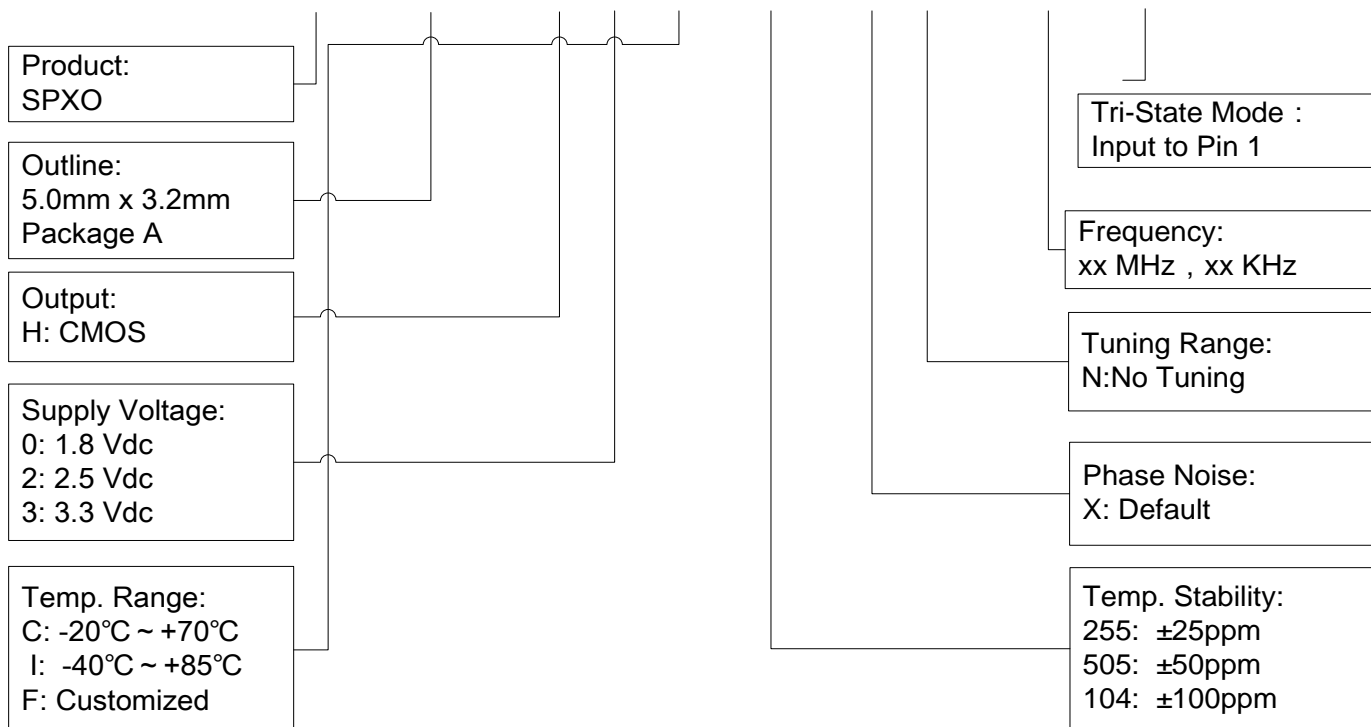
## Outline Dimension & Pin Connections

Unit:  
mm



## Ordering Guide

**BS5032A X X X XXX X XXX.XX X**



**Example: BS5032AD3I505CN20**

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